REMARKS

U.S. Patent No. 6,441,736 B1, as issued, includes Claims 1-18. Claims 1 and 17 are independent claims. By this application for reissue, Claims 19-44 have been added. Thus, Claims 1-44 are now pending.

AMENDMENT TO THE SPECIFICATION

Applicant has amended the specification to claim the benefit of a prior-filed copending application – that is, Serial No. 09/158,290, filed September 22, 1998 (now U.S. Patent No. 6,214,155). This corrects one of the errors upon which this reissue is based.

ORIGINAL CLAIMS 1-18

Applicant has amended Claim 1 to correct a typographical error. Support for this amendment is found at least at Col. 4, lines 6-41.

Applicant submits that original Claims 1-18 are patentable for the same reasons set forth during the prosecution of the application that issued into U.S. Patent No. 6,441,736 B1, which is the subject of this reissue.

NEW CLAIMS 19-44

Support in the Specification for new Claims 19-44 is provided as follows:

CLAIM	SUPPORT
19. A process for incorporating an electronic element in a plastic device, comprising the steps of:	Col. 2, lines 51-67.
(a) providing first and second plastic core sheets;	Col. 3, lines 28-49.
(b) positioning the electronic element between the first and second plastic core sheets to form a core;	Col. 3, lines 28-49.
(c) positioning the core in a laminator apparatus, and subjecting the core to a heat and pressure cycle, the heat and pressure cycle comprising the steps of:	Col. 3, line 50 – Col. 4, line 41.
(I) heating the core;	Col. 4, lines 6-30.
(II) applying a first pressure to the core such that the electronic element is encapsulated by the core; and	Col. 4, lines 6-30.
(III) cooling the core while applying a second pressure to the core.	Col. 4, lines 31-41.

CLAIM	SUPPORT
20. The process of Claim 19, wherein step (c)(III) comprises cooling the core while applying a second pressure to the core, wherein the second pressure is greater than the first pressure.	Col. 4, lines 6-41.
21. The process of Claim 20, wherein step (b) comprises positioning the electronic element in the absence of a non-electronic carrier between the first and second plastic core sheets to form the core.	Col. 3, lines 28-49.
22. The process of Claim 20, wherein step (b) comprises positioning the electronic element in the absence of a non-electronic carrier directly between the first and second plastic core sheets to form the core.	Col. 3, lines 28-49.
23. The process of Claim 19, wherein step (c)(III) comprises cooling the core while applying a second pressure to the core, wherein the second pressure is approximately at least 10% greater than the first pressure.	Col. 4, lines 6-41.
24. The process of Claim 19, wherein step (c)(I) comprises heating the core under a third pressure, wherein the third pressure is less than the first pressure.	Col. 4, lines 6-30.
25. The process of Claim 20, wherein step (c)(II) comprises applying the first pressure uniformly to the core such that the electronic element is encapsulated by the core.	Col. 4, lines 6-30.
26. The process of Claim 20, wherein step (c)(III) comprises cooling the core while applying the second pressure uniformly to the core.	Col. 4, lines 6-41.
27. The process of Claim 20, wherein the electronic element comprises a micro-chip.	Col. 3, lines 5-13.
28. The process of Claim 27, wherein the electronic element further comprises a circuit board antenna.	Col. 3, lines 5-13.
29. The process of Claim 27, wherein the micro-chip includes a protective coating disposed thereon.	Col. 3, lines 5-13.

CLAIM	SUPPORT
30. A process for manufacturing a plastic device that includes an electronic element therein, comprising the steps of:	Col. 2, lines 51-67.
(a) providing first and second plastic core sheets;	Col. 3, lines 28-49.
(b) positioning the electronic element between the first and second plastic core sheets to form a core;	Col. 3, lines 28-49.
(c) positioning the core in a laminator apparatus;	Col. 3, line 50 – Col. 4, line 41.
(d) heating the core;	Col. 4, lines 6-30.
(e) causing the laminator apparatus to apply a first pressure to the core such that the electronic element is encapsulated by the core; and	Col. 4, lines 6-30.
(f) cooling the core while the laminator apparatus applies a second pressure to the core, wherein the second pressure is greater than the first pressure.	Col. 4, lines 31-41.

CLAIM	SUPPORT
31. The process of Claim 30, wherein step (f) comprises cooling the core while the laminator apparatus applies the second pressure to the core, wherein the second pressure is approximately at least 10% greater than the first pressure.	Col. 4, lines 6-41.
32. The process of Claim 31, wherein step (b) comprises positioning the electronic element in the absence of a non-electronic carrier between the first and second plastic core sheets to form the core.	Col. 3, lines 28-49.
33. The process of Claim 31, wherein step (b) comprises positioning the electronic element in the absence of a non-electronic carrier directly between the first and second plastic core sheets to form the core.	Col. 3, lines 28-49.
34. The process of Claim 30, wherein the electronic element comprises a micro-chip.	Col. 3, lines 5-13.
35. The process of Claim 34, wherein the electronic element further comprises a circuit board antenna.	Col. 3, lines 5-13.
36. The process of Claim 34, wherein the micro-chip includes a protective coating disposed thereon.	Col. 3, lines 5-13.

CLAIM	SUPPORT
37. A process for incorporating an electronic element in a plastic device, wherein the electronic element has a top surface and a bottom surface, comprising the steps of:	Col. 2, lines 51-67; Col. 3, lines 5-13.
(a) providing top and bottom plastic core sheets;	Col. 3, lines 28-49.
(b) positioning the electronic element between the top and bottom plastic core sheets to form a core, wherein the top surface of the electronic element is in contact with the top plastic core sheet;	Col. 3, lines 28-49.
(c) positioning the core in a laminator apparatus, and subjecting the core to a heat and pressure cycle, the heat and pressure cycle comprising the steps of:	Col. 3, line 50 – Col. 4, line 41.
(I) heating the core;	Col. 4, lines 6-30.
(II) applying a first pressure to the core so that the electronic element is encapsulated by the core; and	Col. 4, lines 6-30.
(III) cooling the core while applying a second pressure to the core, wherein the second pressure is greater than the first pressure.	Col. 4, lines 31-41.

CLAIM	SUPPORT
38. The process of Claim 37, wherein step (c)(III) comprises cooling the core while applying a second pressure to the core, wherein the second pressure is approximately at least 10% greater than the first pressure.	Col. 4, lines 6-41.
39. The process of Claim 37, wherein step (b) comprises positioning the electronic element between the top and bottom plastic core sheets to form the core, wherein the top and bottom surfaces of the electronic element are in contact with the top and bottom plastic core sheets, respectively.	Col. 3, lines 28-49.
40. The process of Claim 37, wherein step (b) comprises positioning the electronic element in the absence of a non-electronic carrier between the top and bottom plastic core sheets to form the core.	Col. 3, lines 28-49.
41. The process of Claim 37, wherein step (b) comprises positioning the electronic element in the absence of a non-electronic carrier directly between the top and bottom plastic core sheets to form the core.	Col. 3, lines 28-49.
42. The process of Claim 37, wherein the electronic element comprises a micro-chip.	Col. 3, lines 5-13.
43. The process of Claim 42, wherein the electronic element further comprises a circuit board antenna.	Col. 3, lines 5-13.
44. The process of Claim 42, wherein the micro-chip includes a protective coating disposed thereon.	Col. 3, lines 5-13.

Applicant submits that new Claims 19-44 are patentable over the prior art of record.

For the reasons set forth above, applicant submits that all of the pending claims are patentable over the references of record and are in condition for allowance. An early allowance of the claims is earnestly solicited.

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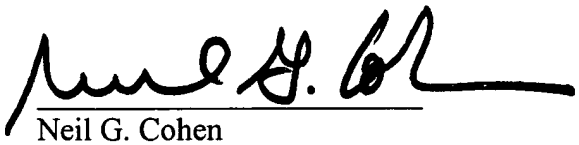
Respectfully submitted,



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